









CEF46N65S

650V ▲ 46mΩ ▲ 46.7ANote 4 ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type
N-channel enhancement mode
UL94V-0 rated flame retardant epoxy

TO220F-3L package ▲ Electrical insulated mounting tab

Super high dense cell density for extremely low R_{DS(ON)}

High power and current handling capability

MAXIMUM RATINGS

Parameter (T _C = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	650V
Gate-Source Voltage	V _{GS}	±20V
Continuous Drain Current at T _C = 25°C	I _D	46.7A Note 4
Continuous Drain Current at T _C = 100°C	I _D	29.5A Note 4
Pulsed Drain Current Note 1	I _{DM} Note 5	187A Note 4
Maximum Power Dissipation at T _C = 25°C	P _D	86W
Power Dissipation Derating above 25°C	ΔP_D	0.69W/°C
Single Pulsed Avalanche Energy Note 6	E _{AS}	300mJ
Single Pulsed Avalanche Current Note 6	I _{AS}	4A
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

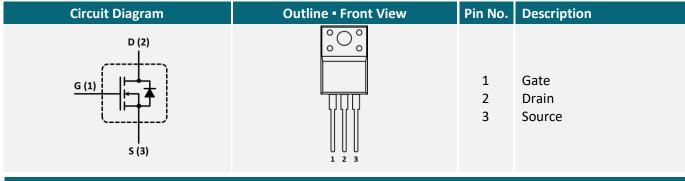
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	1.46°C/W
Thermal Resistance, Junction-to-Ambient	R _{TH JA}	65°C/W

APPLICATIONS

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
₹		-	PFC	*		

PIN DESCRIPTION





ELECTRICAL CHARACTERISTICS ▲ T_C = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV _{DSS}	650			V
Zero Gate Voltage Drain Current	$V_{DS} = 650V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	I_{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -20V, V_{DS} = 0V$	I_{GSSR}			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_{D} = 250 \mu A$	$V_{GS(th)}$	2.5		4.5	V
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 20A$	R _{DS(ON)}		46	56	mΩ
Dynamic Characteristics Note 3						
Input Capacitance	$V_{DS} = 100V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		2935		pF
Output Capacitance	$V_{DS} = 100V, V_{GS} = 0V, f = 1MHz$	Coss		125		pF
Reverse Transfer Capacitance	$V_{DS} = 100V$, $V_{GS} = 0V$, $f = 1MHz$	C _{RSS}		10		pF
Switching Characteristics Note 3						
Turn-On Delay Time	V_{DD} = 520V, V_{GS} = 10V, I_{D} = 10A, $R_{G(ext)}$ = 10 Ω	t _{D(ON)}		45		ns
Turn-On Rise Time	V_{DD} = 520V, V_{GS} = 10V, I_D = 10A, $R_{G(ext)}$ = 10 Ω	t_R		23		ns
Turn-Off Delay Time	V_{DD} = 520V, V_{GS} = 10V, I_D = 10A, $R_{G(ext)}$ = 10 Ω	t _{D(OFF)}		199		ns
Turn-Off Fall Time	V_{DD} = 520V, V_{GS} = 10V, I_D = 10A, $R_{G(ext)}$ = 10 Ω	t _F		10		ns
Total Gate Charge	$V_{DS} = 520V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{G}		100		nC
Gate Source Charge	$V_{DS} = 520V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{GS}		17		nC
Gate Drain Charge	$V_{DS} = 520V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{GD}		41		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode Forward Current		I _S			24.7	Α
Drain-Source Diode Forward Voltage Note 2	V _{GS} = 0V, I _S = 24.7A	V_{SD}			1.5	V
Reverse Recovery Time	$I_D = 20A$, di/dt = 75A/ μ s	t_{RR}		449		ns
Reverse Recovery Charge	$I_D = 20A$, di/dt = 75A/ μ s	Q_{RR}		5.71		μC
Peak Reverse Recover Current	$I_D = 20A$, di/dt = $75A/\mu s$	I_{RR}		21.7		Α

Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: Limited only by maximum temperature allowed.
- 5: Pulse width limited by safe operating area.
- 6: L = 37.5mH, I_{AS} = 5A, V_{DD} = 60V, R_G = 25Ω, Starting T_J = 25°C



REFERENCE DATA A TYPICAL DEVICE PERFORMANCE



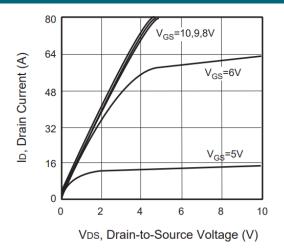


Fig. 2 • Transfer Characteristics

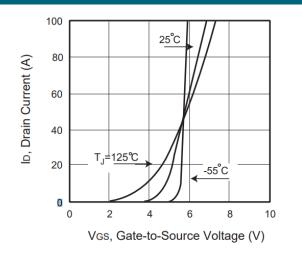


Fig. 3 • Capacitance

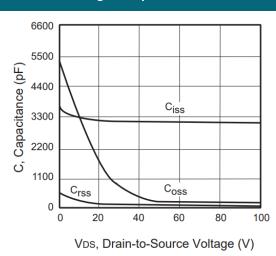


Fig. 4 • On-Resistance Variation with Temperature

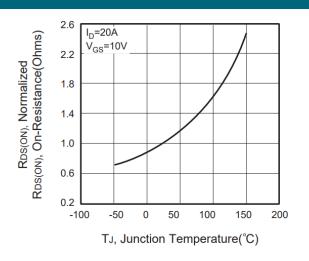


Fig. 5 • Gate Threshold Variation with Temperature

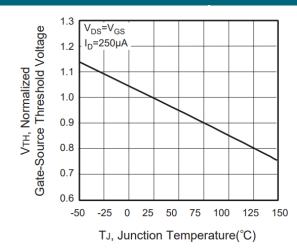
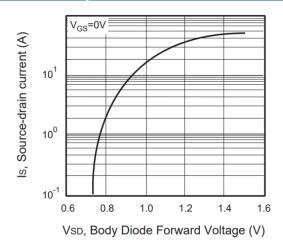


Fig. 6 • Body Diode Forward Voltage Variation with Source Current



MGT ▲ Manufacturer Group of Technology



REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

Fig. 7 • Gate Charge

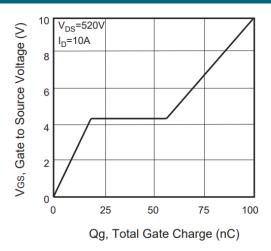


Fig. 8 • Maximum Safe Operating Area

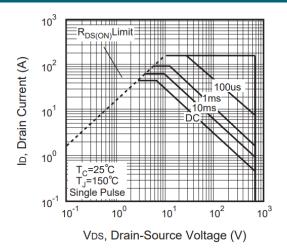
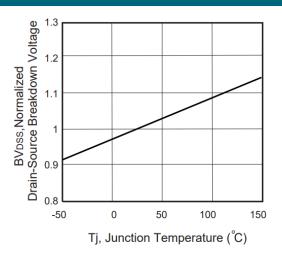


Fig. 9 • Breakdown Voltage Variation vs. Temperature





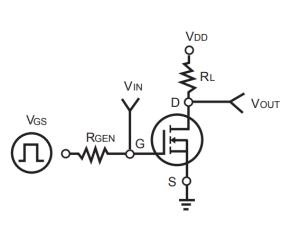
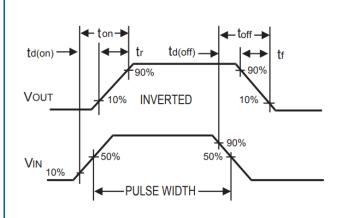


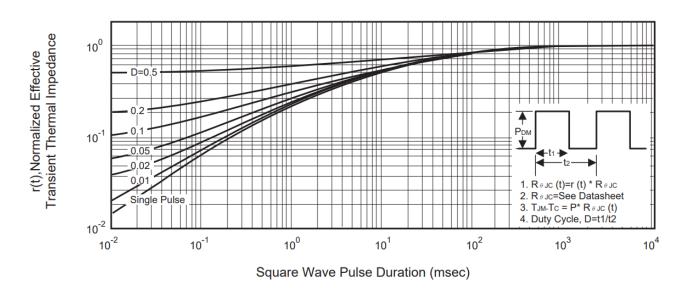
Fig. 11 • Switching Waveforms





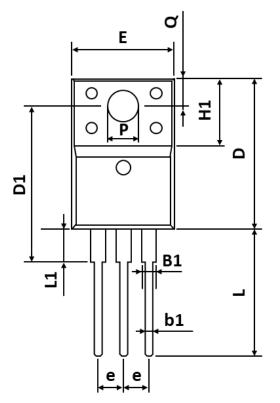
REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

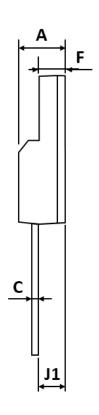
Fig. 12 • Normalized Thermal Transient Impedance Curve





PACKAGE OUTLINE





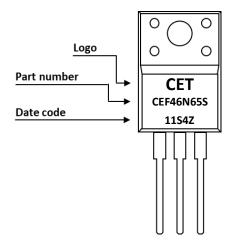
Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
А	4.500	-	5.000
B1	1.000	-	1.500
b1	0.700	-	0.950
С	0.420	-	0.700
D	15.670	-	16.070
D1	14.800	-	16.000
E	9.960	-	10.360
е	2.340	-	2.740
F	2.340	-	2.740
H1	6.480	-	6.900
J1	2.550	-	2.950
L	12.080	-	13.480
L1	2.230	-	3.650
Q	3.100	-	3.500
Р	2.980	-	3.380

ORDERING INFORMATION

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEF46N65S	TO-220F-3L	Tube	50pcs	1,000pcs	4,000pcs

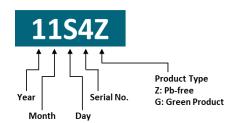


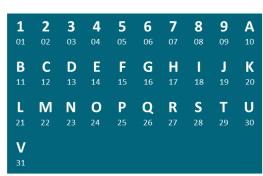
PART MARKING



DATE CODE

Example: 11S4Z



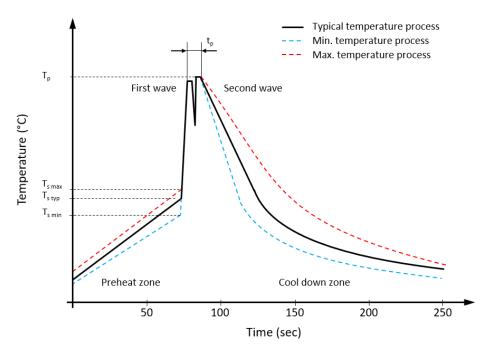


Coding list for "Day"





RECOMMENDED WAVE SOLDERING PROFILE A THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	T_{smin}	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	T_{smax}	130 °C	130 °C
Preheat time t_s from T_{smin} to T_{smax}	ts	70 seconds	70 seconds
Peak temperature	T_p	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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